

preparing said semiconductor package structured by providing a substrate  
for mounting said semiconductor element thereon to fix said semiconductor  
element to one side thereof and a connecting pattern provided on the other side of  
said substrate and by forming a through hole from the one side to the other side of  
said substrate;

*C1  
end*

fixing a surface where the element is formed of said semiconductor element  
to on the one side of said substrate of said semiconductor package such that an  
electrode of said semiconductor element is within said through hole;  
electrically connecting said connecting pattern and said electrode of said  
semiconductor element via wires through said through hole; and  
sealing said through hole and said wires with resin.

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